

West Bond, Inc. *Press Release June 1, 2022*

New Series Wire Bonder



This series is an excellent tool for meeting the challenging bonding applications found in the RF, microwave, semiconductor, hybrid and medical device fields.

The 7KF Bonder is designed with a gantry style chassis enabling virtually unlimited part size capacity. Our exclusive 8:1 ratio, purely orthogonal X-Y-Z Micromanipulator allows the operator of the machine to place bonds very precisely, and with ease.

Convertibility: The 7KF series machines are convertible between Ball Bonding and Wedge Bonding, presenting bond wire at both 45 degrees for optimal loop and tail control, and 90 degrees for deep access and ribbon bonding capabilities. Conversions between setups are made in mere minutes, using a single tool head.

Programmability: The machine features storage for up to 30 device configuration profiles, or buffers, per mode of operation. Each buffer can store up to 21 bonds with individual ultrasonic power, time, force, and loop elevation settings per bond. The programming of each setting, operation of the machine, action prompts, and fault diagnostic information is displayed and input on the machine's 7" capacitive touch sensing LCD.

Features: The 7KF series machines feature programmable force (15-135g), primary and secondary ball sizes, pure vertical Z-motion, and programmable radiant tool heat. High and low frequency versions of the machine are available as the 7KFH and 7KF respectively. The 7KF series uses an open frame design, the 7KFX models remove the base and work platform of the machine and enable mounting the machine to a tabletop or conveyor system. Additionally, risers are available for the machine to support working with extra tall parts.